

Optical Module Sealing Machine



Overview

The fully automatic sealing machine is mainly used for sealing and fusing the outer shell of optical devices, and is suitable for mass production of various TO56, TO46, TO38, EML and other product fusion processes. Even for a combination of different size samples, the sealing process is performed automatically by image recognition. Compared to the resistance welding method, the greatest features of this method are its excellent hermeticity and less influence of stress. The completed. AIT engineered and designed several innovative lid-sealing solutions for optical, thermal, EMI and commercial component and module packaging with outstanding cost effectiveness. It is ideal for the MEMS and wafer level lid sealing applications. Meeting requirements for harsh environments and high performance, hermetic GTMS are. The integrated circuit package shell provides a sealed, stable, and efficient heat dissipation operating environment for the chip through glass-metal and ceramic-metal packaging, protecting the device from humidity, temperature changes, and other physical and chemical environmental conditions.



Article Content

Optical Communication Module Sealing Device

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Lid & Optical Seal

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Optical Sealing and Lid-sealing Solutions for Module packaging MEMS

Optical Sealing and Lid-sealing Solutions Optical Transparent Sealing And Electronic Lid Seals This series of advanced novel low temperature curing sealing solutions offer unparalleled moisture barrier

Seam Sealing

Seam sealing system weld a metal lid to a metal can with a hermetic seal to protect a delicate electronic component, such as a Crystal Device, MEMs, Optical Device, and other sensitive components.

Hermetic sealing of optical module

Hermetic sealing of optical module Abstract A hermetically sealable package may be formed from a top portion and a bottom portion mated along a seam at or near a plane of an optical fiber. A completed

Lid & Optical Seal

Lid & Optical Seal Lid & Optical Seal Solutions Lid Attach Dispensable Insulating and Conductive Adhesive AIT engineered and designed several innovative lid-sealing

Hermetic Optoelectronic Packaging Solutions | INNOVACERA

Leveraging advanced materials and automated processes, our products ensure superior optical signal integrity and long-term reliability, meeting stringent demands in 5G communications, LiDAR systems,

Optical communication Sealing machine Manufacturer & Supplier in

Our Seal welder machine, offering cutting-edge technology and advanced features, provides tight seals to the variety of fiber optic connections that secure it from signal loss or down time using a fiber

Advanced Optical Device Sealing System for Enhanced Protection

The fully automatic sealing machine is mainly used for sealing and fusing the outer shell of optical devices, and is suitable for mass production of various TO56, TO46, TO38, EML and other product

Hermetic sealing of optical device and hybrid IC

Metal lid is placed on ceramic package or metal package, and hermetic sealing is achieved by seam welding. It can be applied to hermetic sealing of packages with various shapes and sizes. Vacuum

Optical Sealing and Lid-sealing Solutions for Module packaging MEMS

This series of advanced novel low temperature curing sealing solutions offer unparalleled moisture barrier and low stress protection to electronics and other devices for the extreme working environments.

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This document is for preliminary research. Verify specifications against current standards, product documentation and project requirements.

